TENTATIVE

TOSHIBA PHOTOCOUPLER GaAlAs IRED + PHOTO-IC

TLP114A(IGM)

TRANSISTOR INVERTOR

INVERTER FOR AIR CONDITIONER

LINE RECEIVER

IPM INTERFACES

The TOSHIBA MINI FLAT COUPLER TLP114A is a small outline coupler, suitable for surface mount assembly.

TLP114A consists of a high output power GaAlAs light emitting diode, optically coupled to a high speed detector of one chip photodiode-transistor.

TLP114A (IGM) has no internal base connection, and a Faraday shield integrated on the photodetector chip provides an effective common mode noise transient immunity.

TLP114A (IGM) guarantees minimum and maximum of propagation delay time, switching time dispersion, and high common mode transient immunity. Therefor TLP114A (IGM) is suitable for isolation interface between IPM (Intelligent Power Module) and control IC circuits in motor control application.

• Isolation Voltage : 3750V_{rms} (Min.)

• Common Mode Transient Immunity

: $\pm 10 \text{kV} / \mu \text{s}$ (Min.) @ $V_{\text{CM}} = 1500 \text{V}$

• Switching Time : t_{pHL} , $t_{pLH} = 0.1 \mu s$ (Min.)

 $=0.8 \mu s$ (Max.)

@ $I_F = 10$ mA, $V_{CC} = 15$ V,

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 $R_{\rm L} = 20 \mathrm{k}\Omega$, $Ta = 25 ^{\circ}\mathrm{C}$

• Switching Time Dispersion : 0.7 μs (Max.)

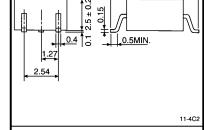
 $(|\mathsf{t}_{\mathsf{p}\mathsf{L}\mathsf{H}}\text{-}\mathsf{t}_{\mathsf{p}\mathsf{H}\mathsf{L}}|)$

• TTL Compatible

• UL Recognized : UL1577, File No.E67349

6 5 4 0 1 3 1 3 3.6 ± 0.2 7.0 ± 0.4

Unit in mm

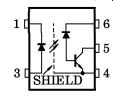


Weight: 0.09g

TOSHIBA

PIN CONFIGURATION (Top view)

11-4C2



1: ANODE

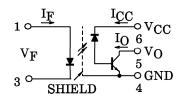
3: CATHODE

4 : EMITTER (GND)

5 : COLLECTOR (OUTPUT)

6 : VCC

SCHEMATIC



MAXIMUM RATINGS (Ta = 25°C)

	CHARACTERISTIC		SYMBOL	RATING	UNIT
	Forward Current	$I_{\mathbf{F}}$	20	mA	
	Pulse Forward Current		$I_{ extbf{FP}}$	40	mA
LED	Peak Transient Forward Current	(Note 3)	I _{FPT} 1		Α
	Reverse Voltage		$v_{ m R}$	5	V
ı	Output Current		I_{O}	8	mA
t o	Peak Output Current	I_{OP}	16	mA	
o e	ο Output Voltage			-0.5~20	V
e t	Supply Voltage		v_{CC}	-0.5~30	V
D	Output Power Dissipation	(Note 4)	P_{O}	100	mW
Op	erating Temperature Range	${ m T_{opr}}$	-55~100	$^{\circ}\mathrm{C}$	
Sto	rage Temperature Range	$\mathrm{T_{stg}}$	-55~125	$^{\circ}\mathrm{C}$	
Lea	ad Soldering Temperature (10s)	T_{sol}	260	$^{\circ}\mathrm{C}$	
Iso	lation Voltage (AC, 1min., R.H.≤60%, Ta=25°C)	(Note 5)	$BV_{\mathbf{S}}$	3750	$v_{ m rms}$

(Note 1): Derate 0.36mA above 70°C.

(Note 2) : 50% duty cycle, 1ms pulse width. Derate $0.72mA/^{\circ}C$ above $70^{\circ}C$.

(Note 3) : Pulse width $PW \le 1\mu s$, 300pps. (Note 4) : Derate 1.8mW/°C above 70°C.

(Note 5): Device considerd a two terminal device: pins 1, 3 shorted together and pins 4, 5, 6 shorted together.

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

	CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
LED	Forward Voltage	$ m V_{ m F}$	$I_{\mathrm{F}} = 16 \mathrm{mA}$	1.22	1.42	1.72	V
	Forward Voltage Temperature Coefficient	ΔV _F /ΔTa	$I_{ m F} = 16 { m mA}$	1	-2	_	mV/°C
]	Reverse Current	$I_{\mathbf{R}}$	I_R $V_R = 5V$		_	10	μ A
	Capacitance between Terminal	C_{T}	$V_{ m F}$ =0, f=1MHz	1	30	_	pF
Detector	High Level Output Current	I _{OH (1)}	$I_{\rm F} = 0$ mA, $V_{\rm CC} = V_{\rm O} = 5.5$ V	1	3	500	nA
		I _{OH} (2)	$I_{\mathbf{F}} = 0$ mA, $V_{\mathbf{CC}} = 30$ V $V_{\mathbf{O}} = 20$ V	_	_	5	
		IOH	I _F =0mA, V _{CC} =30V V _O =20V, Ta=70°C	_	_	50	μ A
	High Level Supply Current	ICCH	I _F =0mA, V _{CC} =30V	-	0.01	1	μ A
	Supply Voltage	v_{CC}	$I_{CC} = 0.01 \text{mA}$	30	_	_	V
	Output Voltage	v_0	$I_{O} = 0.5 \text{mA}$	20	_	_	V

COUPLED ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Current Transfer Ratio	T - /T-	I _F =10mA, V _{CC} =4.5V V _O =0.4V	25	35	75	- %
Current Transfer Ratio	I _O /I _F	I_{F} =16mA, V_{CC} =4.5V V_{O} =0.4V, T_{a} =-25~100°C	15	_	_	
Low Level Output Voltage	v_{OL}	$I_{F}=10mA, V_{CC}=4.5V$ $I_{O}=2.4mA$	_	_	0.4	V

ISOLATION CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Capacitance Input to Output	c_{S}	V=0, f=1MHz (Note 5)	_	0.8	_	pF
Isolation Resistance	RS	R.H. \leq 60%, V _S =500V (Note 5)	5×10 ¹⁰	1014		Ω
		AC, 1 minute	3750	_		$V_{ m rms}$
Isolation Voltage	$BV_{\mathbf{S}}$	AC, 1 second, in oil	_	10000	_	37.1.
		DC, 1 minute, in oil	_	10000	_	Vdc

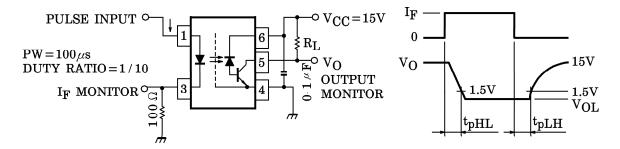
SWITCHING	CHARACTERISTICS	$(Ta = 25^{\circ}C,$	$V_{CC} = 15V$
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CHARACTERISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Propagation Delay Time	t_{pHL}		$I_F = 0 \rightarrow 10 \text{mA}, R_L = 20 \text{k}\Omega$	0.1	0.45	0.8	
(H→L)		PILE		$I_F=0\rightarrow 10$ mA, $R_L=20$ k Ω $T_a=0\sim 85$ °C	0.1	0.45	0.9
Propagation Delay Time $(L \rightarrow H)$	t_{pLH}	1	$I_F=0\rightarrow 10 mA$, $R_L=20 k\Omega$ $T_a=-25\sim 100 ^{\circ}C$	0.1	0.45	1.0	
			$I_F = 10 \rightarrow 0 \text{mA}, R_L = 20 \text{k}\Omega$		0.15	0.7	
Switching Time Dispersion between ON	$ t_{\mathtt{pLH}} - t_{\mathtt{pHL}} $		$I_F=10\rightarrow 0$ mA, $R_L=20$ k Ω $T_a=0\sim 85$ °C	1	0.25	0.8	μs
and OFF			$I_F=10\rightarrow 0$ mA, $R_L=20$ k Ω $T_a=-25\sim 100$ °C		0.25	0.9	
Common Mode Transient Immunity at Logic High Output (Note 6)	CM_{H}		$I_{\mbox{\scriptsize F}}\!=\!0\mbox{\scriptsize mA} \\ V_{\mbox{\scriptsize CM}}\!=\!1500V_{\mbox{\scriptsize p-p}} \\ R_{\mbox{\scriptsize L}}\!=\!20\mbox{\scriptsize k}\Omega$	10000	15000		V/μs
Common Mode Transient Immunity at Logic Low Output (Note 6)	$ m CM_L$	2	$I_F = 10\text{mA}$ $V_{CM} = 1500V_{p-p}$ $R_L = 20\text{k}\Omega$	-10000	-15000		V/μs

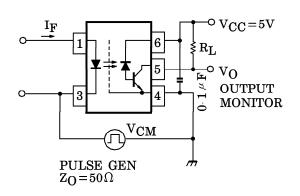
(Note 6): CM_L is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state ($V_O < 1V$). CM_H is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state ($V_O < 4V$).

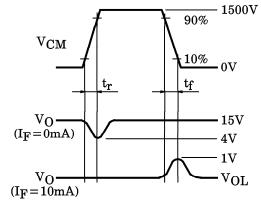
(Note 7): Maximum electrostatic discharge voltage for any pins: 100V (C=200pF, R=0).

TEST CIRCUIT 1 : Switching time test circuit



TEST CIRCUIT 2 : Common mode noise immunity test circuit





$$\mathrm{CM_{H}}\!=\!\frac{1200~\mathrm{(V)}}{\mathrm{t_{r}~(\mu s)}},~\mathrm{CM_{L}}\!=\!\frac{1200~\mathrm{(V)}}{\mathrm{t_{f}~(\mu s)}}$$

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